

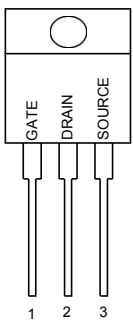


GENERAL DESCRIPTION

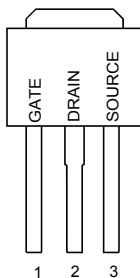
This advanced high voltage MOSFET is designed to withstand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

PIN CONFIGURATION

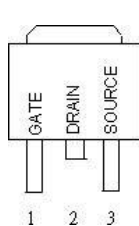
TO-220/TO-220FP
Top View



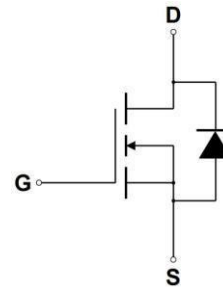
TO-251
Front View



TO-252/ TO-251S
Front View



N-Channel MOSFET



FEATURES

- ◆ SJ MOS
- ◆ Higher Current Rating
- ◆ Lower $R_{ds(on)}$
- ◆ Lower Capacitances
- ◆ Lower Total Gate Charge

SYMBOL

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current — Continuous	$I_{D(1)}$	15	A
— Pulsed	I_{DM}	45	A
Gate-to-Source Voltage — Continue	V_{GS}	± 20	V
Total Power Dissipation TO-251/TO-252/TO-251S	P_D	106.8	W
TO-220		179	
TO-220FP		38	
Derate above 25°C TO-251/TO-252/ TO-251S		0.85	W/°C
TO-220		1.43	
TO-220FP		0.3	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy — $T_J = 25^\circ\text{C}$ ($V_{DD} = 100\text{V}$, $V_{GS} = 10\text{V}$, $I_L = 7.9\text{A}$, $L = 10\text{mH}$)	E_{AS}	312	mJ
Thermal Resistance — Junction to Case TO-251/TO-252/ TO-251S	θ_{JC}	1.17	°C/W
TO-220		0.7	
TO-220FP		3.3	
— Junction to Ambient TO-251/TO-252/ TO-251S	θ_{JA}	100	
TO-220/ TO-220FP		62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	°C

(1) Drain current limited by maximum junction temperature (TO-220)

**ORDERING INFORMATION**

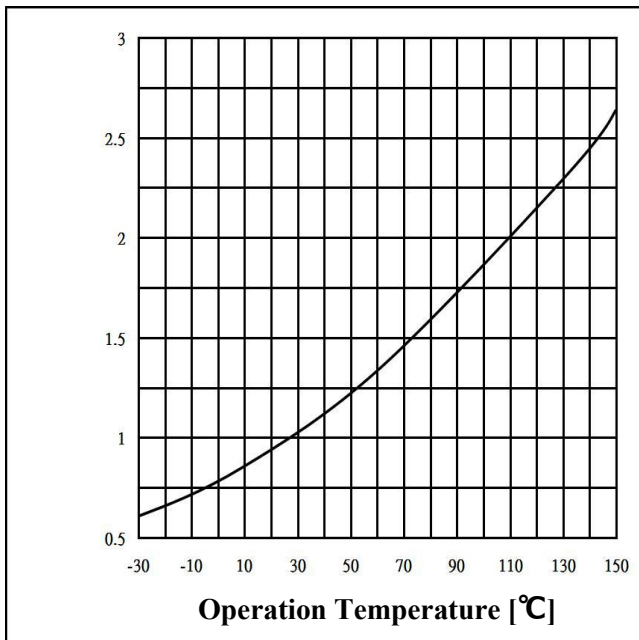
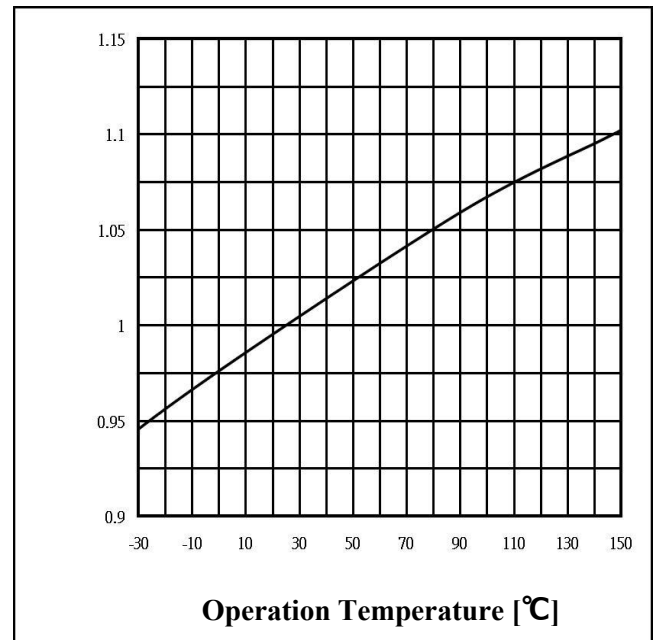
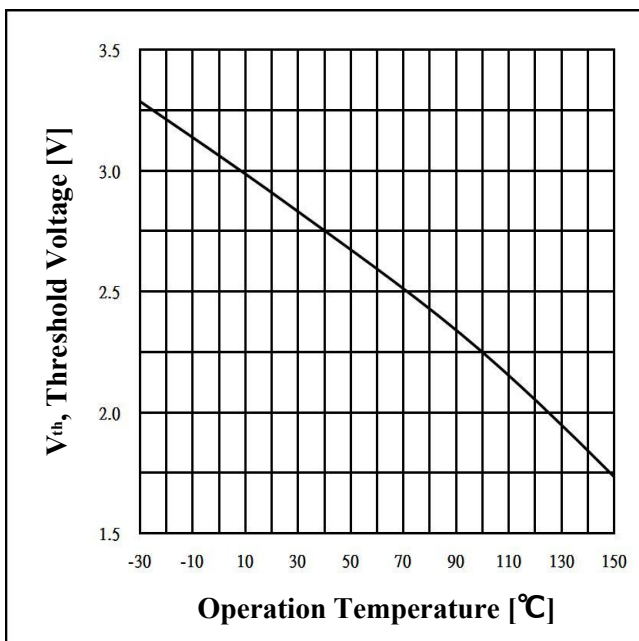
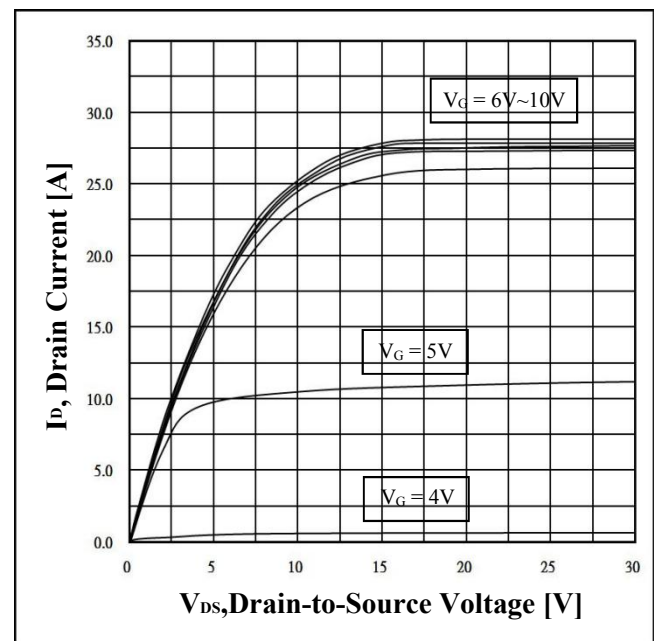
Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM15S65YE	GWM15S65Y	TO-251	Tube	
GWM15S65YF	GWM15S65Y	TO-251S	Tape and Reel	
GWM15S65YD	GWM15S65Y	TO-252	Tube	
GWM15S65YDTR	GWM15S65Y	TO-252	Tape and Reel	
GWM15S65YY	GWM15S65Y	TO-220	Tube	
GWM15S65YX	GWM15S65Y	TO-220FP	Tube	

Note1: Halogen Free and PB Free Product**ELECTRICAL CHARACTERISTICS**Unless otherwise specified, $T_J = 25^{\circ}\text{C}$

		GWM15S65Y				
Characteristic		Symbol	Min	Typ	Max	Units
Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 250 μA)		V _{(BR)DSS}	650			V
Drain-Source Leakage Current (V _{DS} =650V, V _{GS} = 0V)		I _{DSS}			1	uA
Gate-Source Leakage Current-Forward (V _{gsf} = 20V, V _{DS} = 0V)		I _{GSSF}			100	nA
Gate-Source Leakage Current-Reverse (V _{gsr} = - 20V, V _{DS} = 0V)		I _{GSSR}			100	nA
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 250μA)		V _{GS(th)}	2		4	V
Static Drain-Source On-Resistance (V _{GS} = 10V, I _D = 5A) *		R _{DS(on)}			330	mΩ
Input Capacitance	(V _{DS} = 100V, V _{GS} = 0 V, f = 1.0 MHz)	C _{iss}		698		pF
		C _{oss}		36		pF
Output Capacitance	(V _{DS} = 400V, V _{GS} = 0 V, f = 1.0 MHz)	C _{rss}		28		pF
		C _{iss}		695		pF
Reverse Transfer Capacitance		C _{oss}		23		pF
		C _{rss}		11		pF
Turn-On Delay Time	(V _{DD} = 325V, I _D = 15A, V _{GS} = 10V,R _G = 9.1Ω) *	t _{d(on)}		12		ns
Rise Time		t _r		28		ns
Turn-Off Delay Time		t _{d(off)}		30		ns
Fall Time		t _f		7		ns
Total Gate Charge	(V _{DS} = 520V, I _D = 15A, V _{GS} = 10V)*	Q _g		16.4		nC
Gate-Source Charge		Q _{gs}		6		nC
Gate-Drain Charge		Q _{gd}		4.3		nC
SOURCE-DRAIN DIODE CHARACTERISTICS						
Forward On-Voltage(1)	(I _s = 15A, d _{iS} /d _t = 100A/μs)	V _{SD}			1.5	V
Forward Turn-On Time		t _{on}		**		ns
Reverse Recovery Time		t _{rr}		308		ns

* Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

** Negligible, Dominated by circuit inductance

**TYPICAL ELECTRICAL CHARACTERISTICS****Fig 1. On-Resistance Variation with vs. Temperature****Fig.2 Breakdown Voltage Variation vs. Temperature****Fig 3. Threshold Voltage vs. Temperature****Fig 4. Typical Output Characteristics**

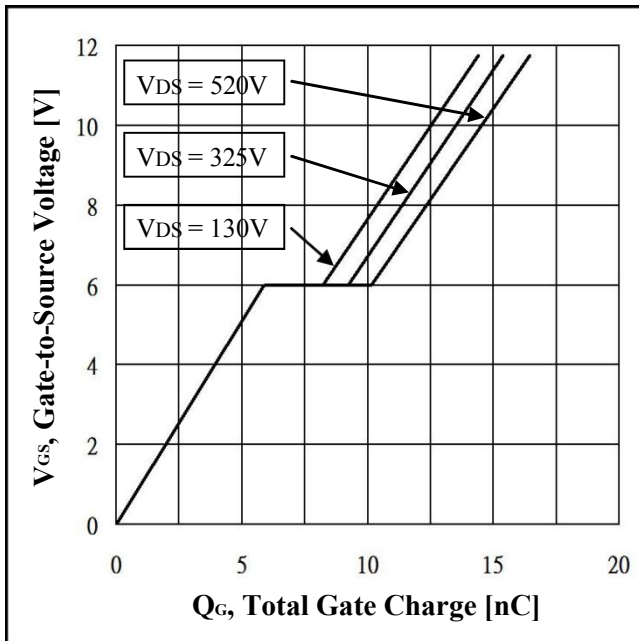


Fig 5. Typical Gate Charge Vs. Gate-to-Source Voltage

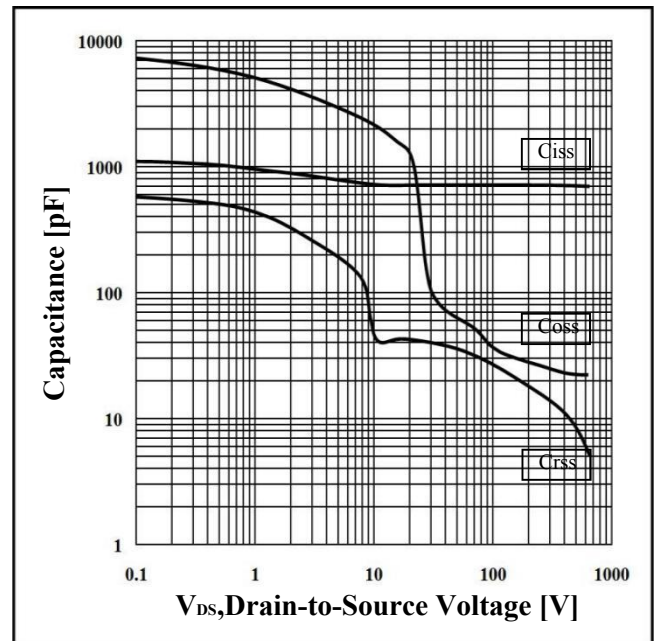


Fig 6. Typical Capacitance Vs. Drain-to-Source Voltage

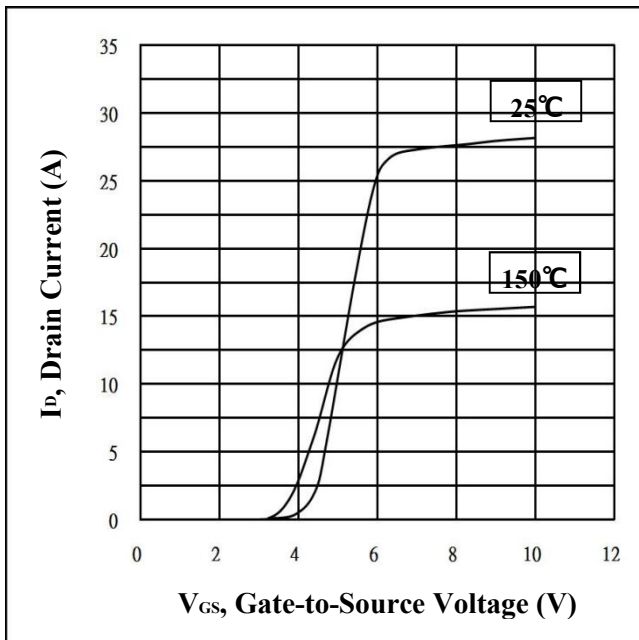


Fig 7. Typical Transfer Characteristics